

## Accelerating Process Innovation

July 26, 2021 — Intel today unveiled one of the most detailed process technology roadmaps that the company has ever provided, showcasing breakthrough technologies that will power its products through 2025 and beyond. Driving the leading edge of technology depends on close collaboration with an ecosystem of partners, including suppliers of advanced fab equipment and research organizations that help bring foundational innovations from the lab to high-volume manufacturing. Intel is privileged to have deep, longstanding partnerships with all of the key players in this ecosystem.

### Supporting quotes

*"Over decades, Applied Materials and Intel have forged a deep partnership to bring transistor and interconnect innovations to life. We look forward to working closely together to accelerate future generations of semiconductor manufacturing as Intel continues to push the limits of technology with its upcoming process and packaging roadmap."*

**Gary Dickerson, president and CEO, Applied Materials**

*"Together, Intel and ASML are on the leading edge of extreme UV lithography technology. As Intel expands its global fab network, we stand ready to supply the cutting edge EUV tools that will contribute to future innovations. We're especially excited about the next-generation High-NA EUV tools, which will enable even greater advances in silicon technology."*

**Peter Wennink, CEO and president, ASML**

*"IBM and Intel share a long history of innovation in cutting-edge semiconductor logic and packaging. The combination of these two storied organizations will continue to push forward the frontiers of technology, from AI to hybrid cloud to next-gen systems. We are excited to collaborate with Intel on critical research to develop the foundational technologies that will support the growth of the entire electronics industry for years to come."*

**Mukesh Khare, vice president, Hybrid Cloud, IBM Research**

*"Together with our partners, imec moves the entire semiconductor ecosystem forward at a rapid pace, collectively tackling the increasing scaling challenges to push Moore's Law beyond 1nm. Among the partners of imec, Intel holds a special place for the entire industry as one of the birth places of innovation in semiconductors. As a strategic partner in our advanced scaling research program, Intel brings unique and valuable knowledge that drives innovation across the broader ecosystem."*

**Luc Van den hove, president and CEO, imec**



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# Quote Sheet

*"Lam Research and Intel have long been at the forefront of driving advances in etch and deposition from development to high-volume production. As Intel pushes its roadmap into the future with exciting new process and packaging innovations, our collaboration becomes even more critical to bring atomic-scale technologies into manufacturing to benefit the entire industry."*

**Tim Archer, president and CEO, Lam Research**

*"CEA-Leti is a recognized global R&D leader in semiconductor technologies. Our close collaboration with Intel over many years has delivered a range of innovations to propel the industry forward. Most recently, our partnership on advanced 3D packaging technologies brings together two semiconductor leaders to advance the state of the art in chiplets, interconnect technologies, and new bonding and stacking capabilities to enable the next generation of high-performance computing applications."*

**Sebastien Dauvé, CEO, CEA-Leti**

*"Building on decades of collaboration, TEL and Intel have continually advanced the state of the art in semiconductor process equipment and materials technology. We are thrilled to see Intel investing in a new generation of process and packaging innovation, and we look forward to working together to drive the leading edge of semiconductor manufacturing."*

**Toshiki Kawai, president and CEO, Tokyo Electron Limited**

## **About Intel**

Intel (Nasdaq: INTC) is an industry leader, creating world-changing technology that enables global progress and enriches lives. Inspired by Moore's Law, we continuously work to advance the design and manufacturing of semiconductors to help address our customers' greatest challenges. By embedding intelligence in the cloud, network, edge and every kind of computing device, we unleash the potential of data to transform business and society for the better. To learn more about Intel's innovations, go to [newsroom.intel.com](https://newsroom.intel.com) and [intel.com](https://intel.com).

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